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FDS8884

N-Channel PowerTrench® MOSFET

30V, **8.5A**, **23m**Ω

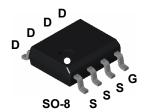
General Descriptions

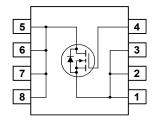
This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low $r_{\text{DS}(\text{on})}$ and fast switching speed.



Features

- Max $r_{DS(on)} = 23m\Omega$ at $V_{GS} = 10V$, $I_D = 8.5A$
- Max $r_{DS(on)} = 30m\Omega$ at $V_{GS} = 4.5V$, $I_D = 7.5A$
- Low gate charge
- 100% R_G Tested
- RoHS Compliant





MOSFET Maximum Ratings $T_A = 25$ °C unless otherwise noted

Symbol	Parameter	Ratings	Units
V_{DS}	Drain to Source Voltage	30	V
V_{GS}	Gate to Source Voltage	±20	V
	Drain Current Continuous (Note 1a)	8.5	Α
ID	Pulsed	40	Α
E _{AS}	Single Pulse Avalanche Energy (Note 2)	32	mJ
В	Power dissipation	2.5	W
P_{D}	Derate above 25°C	20	mW/°C
T _J , T _{STG}	Operating and Storage Temperature	-55 to 150	°C

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	50	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Case	(Note 1)	25	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDS8884	FDS8884	SO-8	330mm	12mm	2500 units

Electrical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	cteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	30			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\mu\text{A}$, referenced to 25°C		23		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 24V$ $V_{GS} = 0V$ $T_{J} = 125^{\circ}C$			1 250	μА
I _{GSS}	Gate to Source Leakage Current	V _{GS} = ±20V			±100	nA

On Characteristics (Note 3)

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	1.2	1.7	2.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25°C		-4.9		mV/°C
		$V_{GS} = 10V, I_D = 8.5A,$		19	23	
race	Drain to Source On Resistance	$V_{GS} = 4.5V$, $I_{D} = 7.5A$,		23	30	mΩ
r _{DS(on)}	Brain to course on resistance	$V_{GS} = 10V, I_D = 8.5A,$ $T_J = 125^{\circ}C$		26	32	11152

Dynamic Characteristics

C _{iss}	Input Capacitance	V 45V V 0V	475	635	pF
C _{oss}	Output Capacitance	V _{DS} = 15V, V _{GS} = 0V, f = 1MHz	100	135	рF
C _{rss}	Reverse Transfer Capacitance	1 – 1101112	65	100	pF
R_G	Gate Resistance	f = 1MHz	0.9	1.6	Ω

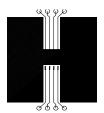
Switching Characteristics (Note 3)

t _{d(on)}	Turn-On Delay Time		5	10	ns
t _r	Rise Time	$V_{DD} = 15V, I_D = 8.5A$ $V_{GS} = 10V, R_{GS} = 33\Omega$	9	18	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10V, H_{GS} = 3312$	42	68	ns
t _f	Fall Time		21	34	ns
Q _g	Total Gate Charge	$V_{DS} = 15V, V_{GS} = 10V$ $I_{D} = 8.5A$	9.2	13	nC
Q_g	Total Gate Charge	$V_{DS} = 15V, V_{GS} = 5V$	5.0	7	nC
Q _{gs}	Gate to Source Gate Charge	I _D = 8.5A	1.5		nC
Q _{gd}	Gate to Drain Charge		2.0		nC

Drain-Source Diode Characteristics

V 6	Source to Drain Diode Voltage	I _{SD} = 8.5A	0.9	1.25	V
V_{SD}	Source to Drain Diode Voltage	I _{SD} = 2.1A	0.8	1.0	V
t _{rr}	Reverse Recovery Time	$I_F = 8.5A$, di/dt = 100A/ μ s		33	ns
Q _{rr}	Reverse Recovery Charge			20	nC

^{1:} R_{B,IA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{B,C} is guaranteed by design while R_{B,CA} is determined by the user's board design.



a) 50°C/W when mounted on a 1 in2 pad of 2 oz copper



b) 105°C/W when mounted on a .04 in² pad of 2 oz copper



c) 125°C/W when mounted on a minimun pad

Scale 1: 1 on letter size paper

2: Starting $T_J=25^{\circ}C$, L = 1mH, I_{AS} = 8A, V_{DD} = 27V, V_{GS} = 10V. 3: Pulse Test:Pulse Width <300 μ S, Duty Cycle <2%.



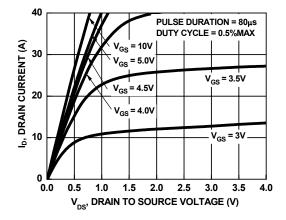


Figure 1. On Region Characteristics

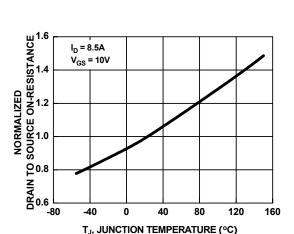


Figure 3. Normalized On Resistance vs Junction Temperature

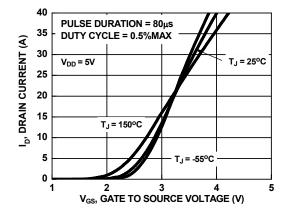


Figure 5. Transfer Characteristics

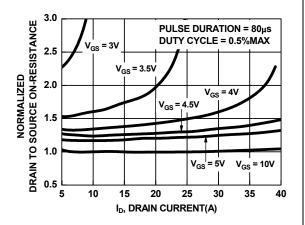


Figure 2. Normalized On-Resistance vs Drain current and Gate Voltage

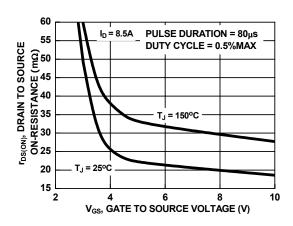


Figure 4. On-Resistance vs Gate to Source Voltage

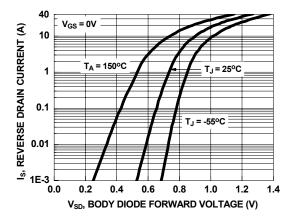


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

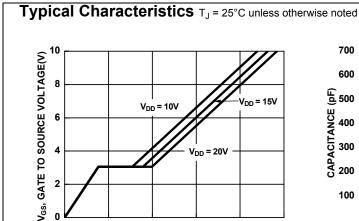


Figure 7. Gate Charge Characteristics

6

Q_g, GATE CHARGE(nC)

8

10

0

2

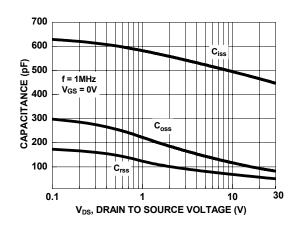


Figure 8. Capacitance vs Drain to Source Voltage

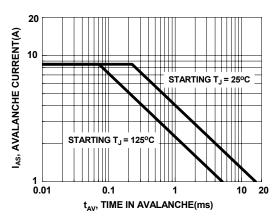


Figure 9. Unclamped Inductive Switching Capability

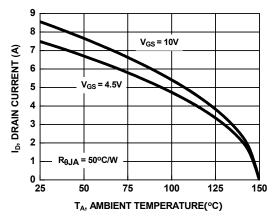


Figure 10. Maximum Continuous Drain Current vs **Ambient Temperature**

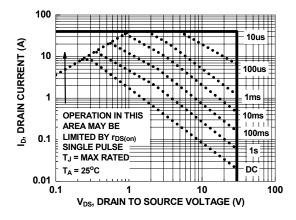


Figure 11. Forward Bias Safe Operating Area

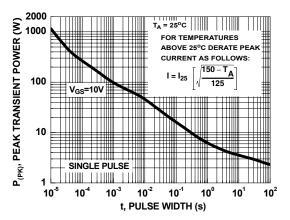


Figure 12. Single Pulse Maximum Power Dissipation

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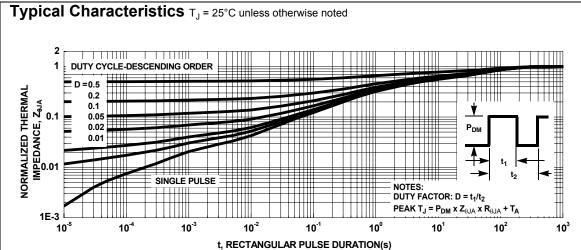


Figure 13. Transient Thermal Response Curve

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